

## DESCRIPTION

The IS32LT3120 is a linear programmable current regulator consisting of 2 output channels capable of up to 200mA each. Each channel features an ON/OFF input pin to toggle the channel between the OFF condition and the source condition.

The device integrates 63 steps fade in and fade out algorithm (Gamma correction) which causes the output LED current to gradually ramp up to the full source value after the channel's control pin is pulsed. The same controller causes the LED current to gradually ramp down to zero if the channel's input control pin is pulsed while the output channel is on.

#### FEATURES

- Dual output channels source up to 200mA each
- Independent debounced ON/OFF control for each channel
- Programmable current via a single external resistor
- Programmable fade in, fade out via external resistor
  - Pull down resistor value sets fade speed
  - Gamma corrected fade in/out algorithm
- Fault Protection:
  - LED string shorted to GND
  - Over temperature
- SOP-8-EP packages
- Automotive Grade AEC-Q100 (pending)
- Operating temperature range from -40°C ~ +125°C

### QUICK START



Figure 1: Photo of IS32LT3120 Evaluation Board

#### **RECOMMENDED EQUIPMENT**

• 12V,1A DC power supply

### **ABSOLUTE MAXIMUM RATINGS**

≤ 45V power supply

Caution: Do not exceed the conditions listed above, otherwise the board will be damaged.

#### PROCEDURE

The IS32LT3120 evaluation board is fully assembled and tested. Follow the steps listed below to verify board operation.

# Caution: Do not turn on the power supply until all connections are completed.

- Connect the ground terminal of the power supply to the GND and the positive terminal to the VCC.
  **NOTE:** The VCC supply should be set close to the IS32LT3120 minimal headroom voltage of 0.5V (Vcc – Voutx) for best thermal performance. The board can be operated with a larger headroom voltage as long as the increase in package temperature is monitored. Exceeding the device package temperature specification will cause the device to enter thermal protection mode.
- 2) The fade time of both channels is adjusted by the variable resistor (RW1).Turn RW1 counter clockwise to decrease fade time, and clockwise to increase fade time. Once the desired fade time is set, measure the resistor value across TP1 and GND. Use this measured resistor value to replace the variable resistor RW1 and R3 (see schematic Figure 2).
- 3) The output current of both channels (OUT1 and OUT2) is adjusted by the variable resistor (RW2). Turn RW2 counter clockwise to decrease the output current of both channels, and clockwise to increase the output current of both channels. The test point TP2 can be used to detect the resistor value at the ISET pin. The final resistance can be measured with an ohm meter across TP2 and GND pins. Use this measured resistor value to replace the variable resistor RW2 and R4 (see schematic Figure 2).
- 4) Momentary contact buttons (K1, K2) are used to individually enable/disable the Outx LED channels. Press K1 to enable the onboard LED string for channel 1. Press K2 to enable the onboard LED string for channel 2. In both cases wait for the LED string to be fully ON (fade time completed) before pressing the button (K1 or K2) to turn OFF the corresponding LED string. Always wait for completion of fade time before pressing either K1 or K2.
- 5) JP1is used to connect the IS32LT3120 Out 1 (pin 4) to the onboard LED string (LED1, LED3 and LED5). JP2 connects the device Out2 (pin 5) to the onboard LED string (LED2, LED4, LED6). Use one of the green terminal blocks to connect an external LED string. Remove the corresponding jumper header (JP1 or JP2) to disable the onboard LED string. *Note:* Connecting an external LED string without removing the onboard string jumper header will drive both onboard and external LED strings in parallel resulting in lower current drive to both strings.



6) The on board LED string size can be adjusted from 1 to 3 LEDs by using jumper headers JP3~JP6. Connecting the header to pins 2-3 disables the corresponding LED, ie JP3 pins 2-3 disables LED3. To enable all the LED3~LED6 connect JP3~JP6 to pins 1-2.

#### ORDERING INFORMATION

Part No.	Temperature Range	Package
IS32LT3120-GRLA3-EB	-40°C ~ +125°C (Automotive)	SOP-8-EP, Lead-free

Table1: Ordering Information

For pricing, delivery, and ordering information, please contact ISSI's analog marketing team at <u>analog@issi.com</u> or (408) 969-6600

#### EVALUATION BOARD OPERATION

IS32LT3120 evaluation board drives two strings of WLEDs. There are two variable resistors used for adjusting the fade time (RW1), LED current (RW2).

### SETTING THE FADE TIME

The fade time, either in or out, for both channels is the same, and is set by a single external programming resistor ( $R_{TSET}$ ). The fade time is programmable by Equation (1):

$$t \approx R_{TSET} \times 2.5\,\mu s \tag{1}$$

For example,  $R_{TSET}$ =100k $\Omega$ , fade time is about 0.25s.

Note: In order to get the optimized effect, the recommended fading time is between 1.5s (RTSET=600 $k\Omega$ ) and 0.25s (RTSET=100 $k\Omega$ ).

If the TSET pin is tied directly to GND, the fade in/out function is canceled and the ramp time is about 73µs, or 'instant on'. However, the debounce feature of the ENx pin is not disabled.

### **OUTPUT CURRENT SETTING**

A single programming resistor ( $R_{ISET}$ ) controls the maximum output current for both output channels simultaneously. The programming resistor may be computed using the following Equation:

$$R_{ISET} = \frac{2000}{I_{SET}} (10k\Omega \le R_{ISET} \le 100k\Omega)$$

The device is protected from an output over current condition caused by an accidental short circuit of the ISET pin, by internally limiting the maximum current in the event of an ISET short circuit to 260mA.

### THERMAL ROLLOFF

The output current of both channels will be equal to the set value so long as the die temperature of the IC remains below  $125^{\circ}C$  (Typical). If the die temperature exceeds this threshold, the output current of the device will begin to reduce at a rate of  $3\%/^{\circ}C$ .

The roll off slope is related to ISET value. When  $I_{SET}$ =20mA, the roll off slope is about 3.7%. When  $I_{SET}$ =200mA, the roll off slope is about 2.2%

### FAULT DETECTION

An output shorted to GND fault is detected if the output voltage on a channel drops below the low voltage threshold  $V_{SCD}$  and remains below the threshold for  $t_{FD}$ . The channel (OUTx) with the short condition will reduce its output current to 20% of  $I_{SET}$ .

When short condition is removed, output current will recover to original value.

When output current is larger than limit value, about 260mA, the output current will be clamped. When the open fault condition is recovered, there will be a large current pulse about  $10\mu s$ .



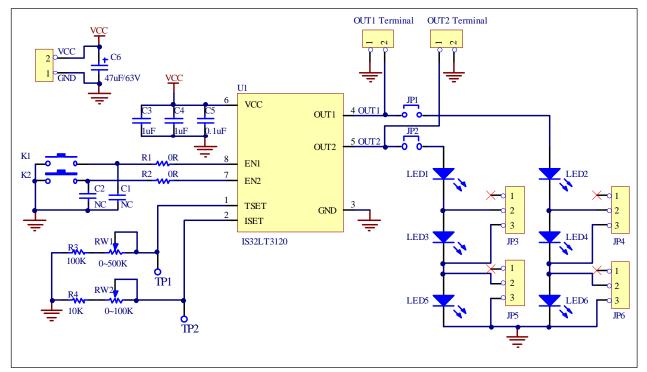


Figure 2: IS32LT3120 Application Schematic

# **BILL OF MATERIALS**

Name	Symbol	Description	Qty	Supplier	Part No.
LED Driver	U1	LED Driver	1	ISSI	IS32LT3120
Resistor	R3	RES,100k,1/8W,±1%,SMD	1	YAGEO	RC1206FR-07100KL
Resistor	R4	RES,10k,1/8W,±1%,SMD	1	YAGEO	RC1206FR-0710KL
Resistors	R1,R2	RES,0ohm,1/16W,±5%,SMD	2	YAGEO	RL0603JR-0700RL
Variable Resistor	RW1,	RES,0~500K	1		
Variable Resistor	RW2	RES,0~100K	1		
Capacitor	C6	CAP,47µF,63V,±20%,SMD	1		
Capacitor	C5	CAP,0.1µF,50V,±10%,SMD	1	YAGEO	CC0603JKX7R9BB104
Capacitor	C3,C4	CAP, 1µF,50V,±10%,SMD	2	YAGEO	CC0805JKX7R9BB105
Button	K1,K2	Momentary Button SMD	2		
Terminal blocks	OUT1,OUT2	green terminal blocks	2		

Bill of materials, refer to Figure 2 above.



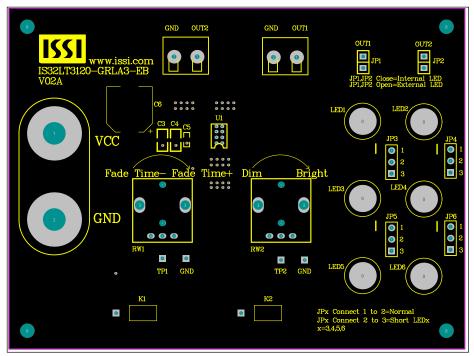


Figure 3: Board Component Placement Guide -Top Layer

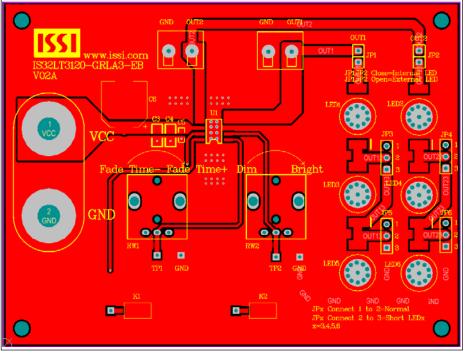


Figure 4: Board Component Placement Guide -Top Layer



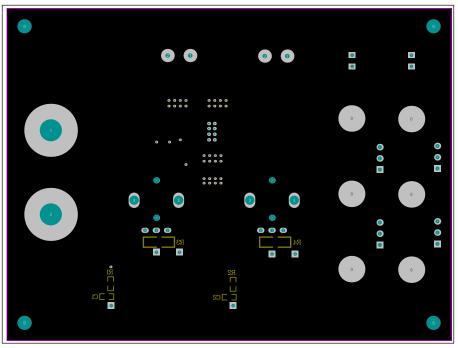


Figure 5: Board PCB Layout- Top Layer

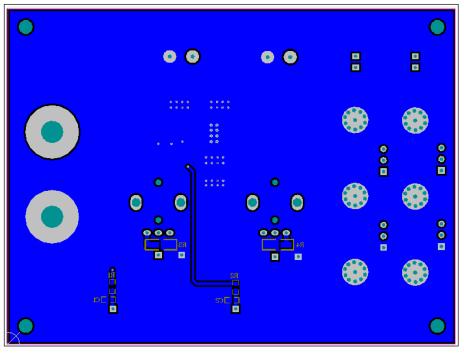


Figure 6: Board PCB Layout- Top Layer

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